



PK596 (v1.0) February 15, 2013

100% Material Declaration Data Sheet for 7 Series CLG400 Package

Average Weight: 0.9090 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.025878	2.847
	Silicon	7440-21-3	100.00		0.025878	
Die Attach Material					0.008105	0.892
	Silver	7440-22-4	77.50		0.006281	
	Bismaleimide monomer	Trade Secret	15.00		0.001216	
	Acrylate monomer	Trade Secret	7.50		0.000608	
Mold Compound					0.376323	41.400
	Epoxy Resin	Trade secret	5.00		0.018816	
	Phenol Resin	Trade secret	3.00		0.011290	
	Phenol Novolac	9003-35-4	3.00		0.011290	
	Metal Hydroxide	Trade Secret	3.00		0.011290	
	Carbon black	1333-86-4	0.30		0.001129	
	Silica fused	60676-86-0	70.40		0.264931	
	Silica Dioxide	7631-86-9	15.00		0.056448	
	Silica, crystalline	14808-60-7	0.30		0.001129	
Copper Wire					0.005401	0.594
	Copper	7440-50-8	98.20		0.005304	
	Palladium	7440-05-3	1.80		0.000097	
Solder Ball					0.193372	21.273
	Tin	7440-31-5	96.50		0.186604	
	Silver	7440-22-4	3.00		0.005801	
	Copper	7440-50-8	0.50		0.000967	
Substrate					0.299922	32.995
	Gold	7440-57-5	0.18		0.000540	
	Nickel	7440-02-0	1.63		0.004889	
	Copper	7440-50-8	43.97		0.131876	
	Glass Fiber	65997-17-3	21.29		0.063853	
	Non halogen fire retardant	Trade Secret	0.01		0.000030	
	BT core	105391-33-1 25722-66-1 Trade Secret	26.01		0.078010	
	Solder Mask	34590-94-8 7727-43-7 Trade Secret	6.90		0.020695	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
02/15/2013	1.0	Xilinx Initial Release

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